

P series

Non-UV Curable Back-Grinding Tape

Adwill P-Series of non-UV curable back-grinding tapes fully protects the wafer surface during grinding and prevents wafer surface contamination from infiltration of grinding fluid and/or debris.

P-Series tapes perform with virtually no residual adhesive after the tape is peeled off, while its highly precise tape thickness accuracy ensures uniform wafer thickness after back-grinding.

Process	Application	Base Material	Tape Name
Back-Grinding	Standard Si Grinding (wafer thickness after grinding >75 µm)	PO	P-4140A / P-4205B / P-6130
	Thin Si Grinding (wafer thickness after grinding >40 µm)	Special Elastomer	P-7125*
	Compound Semiconductor (SiC, GaN, etc.)	PO	P-6130
		Special Elastomer	P-7181